Machine	KLA&TENCOR P22 PROFILER
Machine S/N	[redacted]
Electric source	230V/5A/1PH/50Hz
Wafer Size	6 "/8"
Dimension	78*115*54CM/Anti-vibration table:84*122*85
Air	CDA
Features	- Automated Surface Profilemeter - Automated Wafer Handler - Computer Controlled - Scan Method: Moving Stage, Stationary Stylus - Scan Speed: 1 µm/sec to 25 mm/sec (0.04 mil/sec to 1 in/sec) - Sampling Rate: 50, 100, 200, 500, 1000 sample/sec nominal - Vertical Ranges - Resolution: ±3.2 µm / 0.5 Å (±0.13 mil/0.002 µin), ±13 µm / 2 Å (±0.51 mil/0.008 µin), 130 µm / 10 Å (±5.1 mil/0.04 µin) - Vertical Linearity: ±0.5% above 2000 Å, 10 Å below 2000 Å - Stylus Control: Programmable Force - MHII Range: 0.05-50 mg - Resolution: 0.1 mg - Programmable Descent Rate - Dual View Optics - Side View Optics 150-600x - Top View Optics 185-750x and 300-1200x (with User Interchangeable Lens) - Operations Manual
Configuration:	Automated Surface Profilometer, Calibrated to OEM Specifications, 8"/200mm Wafers, Automated Handler